

IN THE CLAIMS:

Please cancel claims 1-22 without prejudice, and add new claims 23-30 as follows:

1-22. (Canceled)

23. (New) A method of polishing a substrate surface comprising:

(a) contacting the substrate surface with a polishing sheet comprising one or more of CeO_2 and alumina, the polishing sheet comprising:

(i) a polishing surface including a plurality of projecting surface features, wherein the projecting surface features include the one or more of CeO_2 and alumina, the polishing sheet comprising a material at least semi-transparent to laser light with a wavelength of about 670 nm;

(ii) a region for monitoring reflected light, the region having no projecting surface features;

(b) moving the polishing sheet relative to the substrate surface to polish the substrate surface; and

(c) determining an amount of material removed from the substrate surface by:

(i) measuring an intensity of reflected light from the substrate through the region having no projecting surface features.

24. (New) The method according to claim 23, wherein the region having no projecting surface features does not include the one or more of CeO_2 and alumina.

25. (New) The method according to claim 23, wherein the region having no projecting surface features is a discrete region that extends over an entire length of the polishing sheet.

26. (New) The method according to claim 23, wherein the region having no

projecting surface features is a discrete region that extends over a limited length of the polishing sheet.

27. (New) The method according to claim 26, wherein the discrete region is rectangular.

28. (New) The method according to claim 23, wherein the determining an amount of material removed comprises monitoring variations in the reflected light.

29. (New) The method according to claim 23, wherein the polishing sheet is a continuous belt.

30. (New) The method according to claim 23, wherein the polishing sheet is linear and unwound from a roll.